

Product Summary

B320AF/B330AF

Product	V _{RRM} (V)	I _O (A)	V _{F(MAX)} (V) @ +25°C	I _{R(MAX)} (mA) @ +25°C
B320AF	20	3	0.50	0.20
B330AF	30	3	0.50	0.20

Description and Applications

The Schottky providing low V_F and excellent reverse leakage stability at high temperatures, this device is ideal for use in general rectification applications such as:

- Boost Diodes
- Blocking Diodes
- Recirculating Diodes

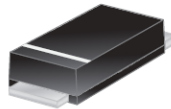
Features and Benefits

- Reduced Low Forward Voltage Drop (V_F); Better Efficiency and Cooler Operation
- Reduced High-temperature Reverse Leakage; Increased Reliability against Thermal Runaway Failure in High Temperature Operation
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: SMAF
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.036 grams (Approximate)

SMAF



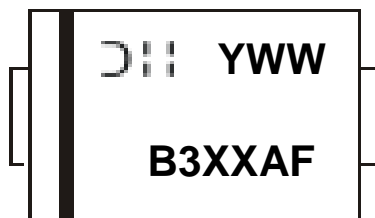
Top View

Ordering Information (Note 4)

Part Number	Case	Packaging
B320AF-13	SMAF	10,000/Tape & Reel
B330AF-13	SMAF	10,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



B3XXAF = Product Type Marking Code, ex: B320AF
 DII = Manufacturers' Code Marking
 YWW = Date Code Marking
 Y = Last Digit of Year (ex: 7 for 2017)
 WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	B320AF	B330AF	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	20	30	V
Working Peak Reverse Voltage	V _{RWM}			
DC Blocking Voltage	V _{RM}			
Average Rectified Output Current	I _O	3		A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	80		A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	85	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R _{θJC}	45	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition	
Forward Voltage Drop	V _F	—	0.46 0.40	0.50 —	V	I _F = 3A, T _J = +25°C I _F = 3A, T _J = +125°C	
Leakage Current (Note 6)	I _R	—	B320AF	0.02	0.20	mA	V _R = 20V, T _J = +25°C
			B330AF	12	—		V _R = 20V, T _J = +125°C
			—	0.03	0.20		V _R = 30V, T _J = +25°C
			—	14.0	—		V _R = 30V, T _J = +125°C
Typical Capacitance	C _T	—	140	—	pF	V _R = 4.0V, f = 1MHz	

Notes: 5. Device mounted on FR-4 substrate, 0.4"×0.5", 2oz, single-sided, PC boards with 0.2"×0.25" copper pad.
6. Short duration pulse test used to minimize self-heating effect.

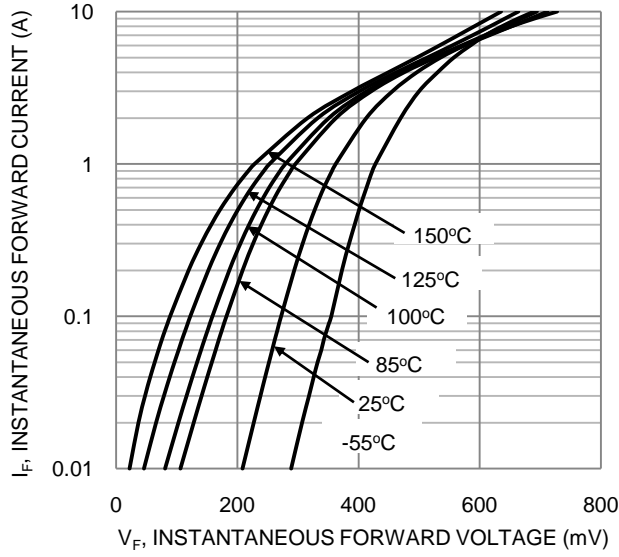


Figure 1. Typical Forward Characteristics

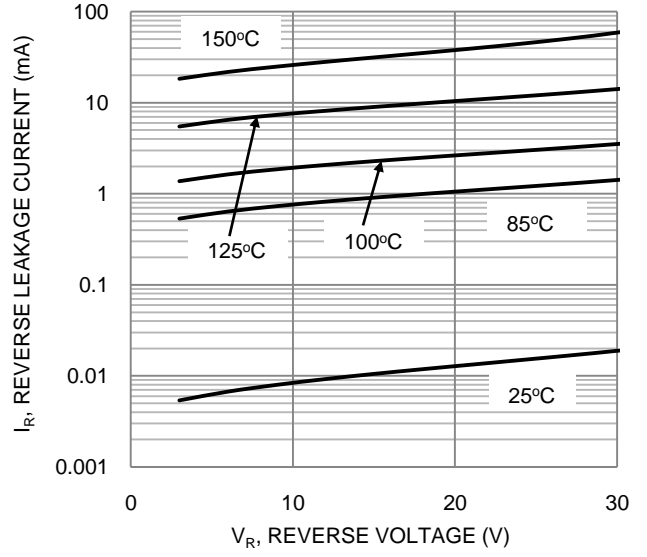


Figure 2. Typical Reverse Characteristics

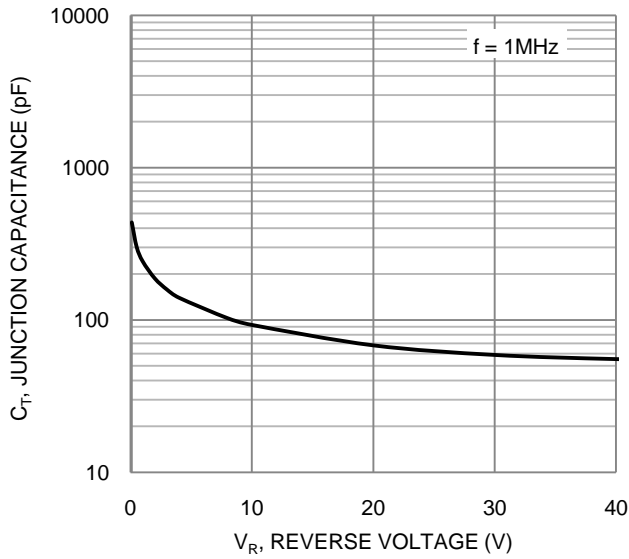


Figure 3. Typical Junction Capacitance

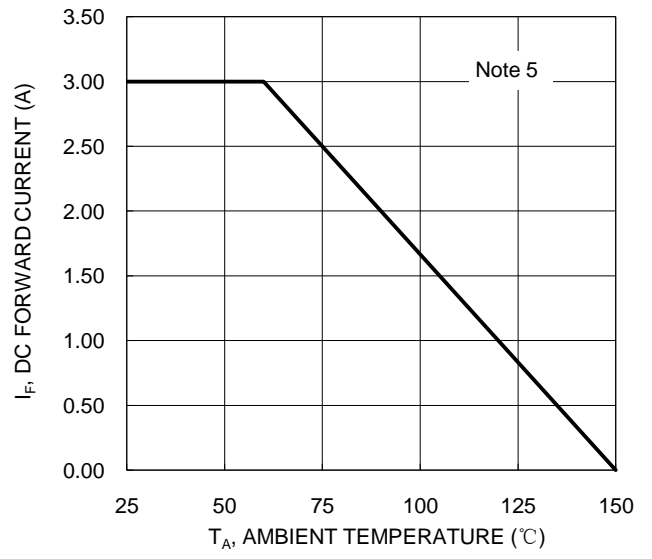
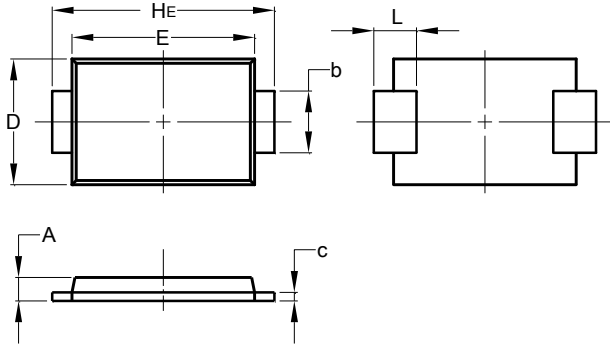


Figure 4. DC Forward Current Derating

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMAF



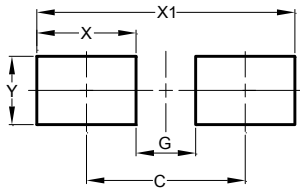
SMAF		
Dim	Min	Max
A	0.90	1.10
b	1.25	1.65
c	0.10	0.40
D	2.25	2.95
E	3.95	4.60
HE	4.80	5.60
L	0.50	1.50
All Dimensions in mm		

NEW PRODUCT

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMAF



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

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